

LOW-VOLTAGE 1:10 LVPECL WITH SELECTABLE INPUT CLOCK DRIVER

Check for Samples: [CDCLVP111-EP](#)

FEATURES

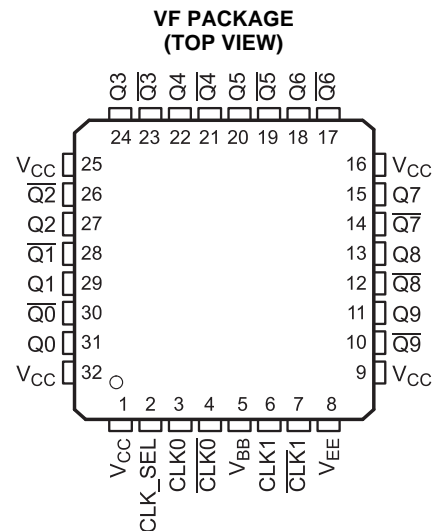
- Distributes One Differential Clock Input Pair LVPECL to 10 Differential LVPECL
- Fully Compatible With LVECL and LVPECL
- Supports a Wide Supply Voltage Range From 2.375 V to 3.8 V
- Selectable Clock Input Through CLK_SEL
- Low-Output Skew (Typ 15 ps) for Clock-Distribution Applications
 - Additive Jitter Less Than 1 ps
 - Propagation Delay Less Than 355 ps
 - Open Input Default State
 - LVDS, CML, SSTL input compatible
- V_{BB} Reference Voltage Output for Single-Ended Clocking
- Available in a 32-Pin LQFP Package
- Frequency Range From DC to 3.5 GHz
- Pin-to-Pin Compatible With MC100 Series EP111, ES6111, LVEP111, PTN1111

APPLICATIONS

- Designed for Driving 50 Ω Transmission Lines
- High Performance Clock Distribution

SUPPORTS DEFENSE, AEROSPACE, AND MEDICAL APPLICATIONS

- Controlled Baseline
- One Assembly and Test Site
- One Fabrication Site
- Available in Military (-55°C to 125°C) Temperature Range ⁽¹⁾
- Extended Product Life Cycle
- Extended Product-Change Notification
- Product Traceability



(1) Custom temperature ranges available

DESCRIPTION

The CDCLVP111 clock driver distributes one differential clock pair of LVPECL input, (CLK0, CLK1) to ten pairs of differential LVPECL clock (Q0, Q9) outputs with minimum skew for clock distribution. The CDCLVP111 can accept two clock sources into an input multiplexer. The CDCLVP111 is specifically designed for driving 50- Ω transmission lines. When an output pin is not used, leaving it open is recommended to reduce power consumption. If only one of the output pins from a differential pair is used, the other output pin must be identically terminated to 50 Ω .

The V_{BB} reference voltage output is used if single-ended input operation is required. In this case, the V_{BB} pin should be connected to CLK0 and bypassed to GND via a 10-nF capacitor.

However, for high-speed performance up to 3.5 GHz, the differential mode is strongly recommended.

The CDCLVP111 is characterized for operation from -55°C to 125°C .



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Table 1. FUNCTION TABLE

CLK_SEL	ACTIVE CLOCK INPUT
0	CLK0, $\overline{\text{CLK0}}$
1	CLK1, $\overline{\text{CLK1}}$

Table 2. ORDERING INFORMATION⁽¹⁾

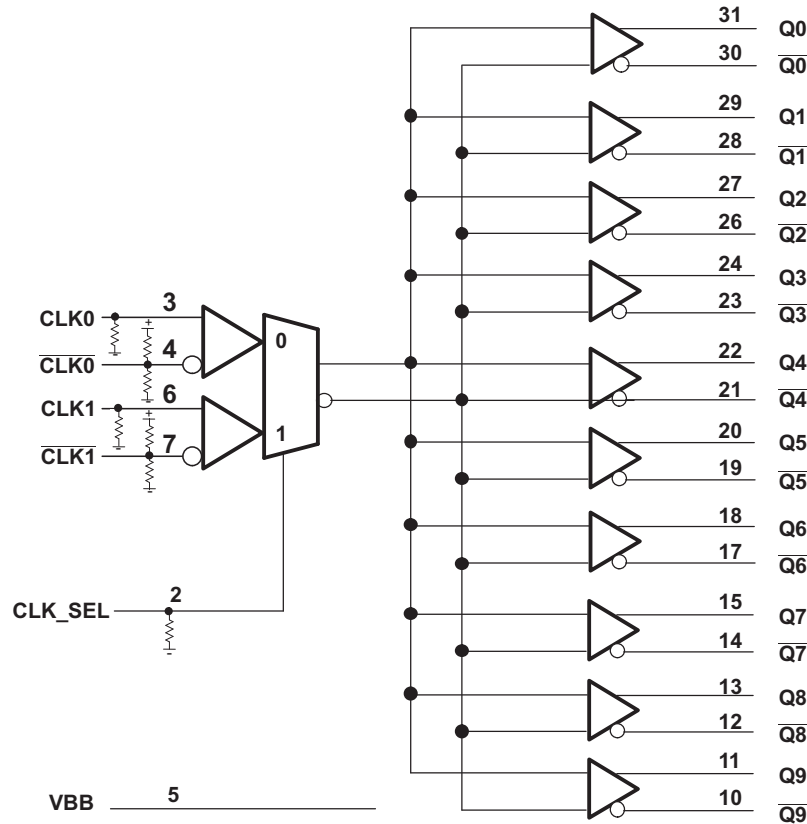
T _J	PACKAGE	ORDERABLE PART NUMBER	TOP-SIDE MARKING	VID NUMBER
–55°C to 125°C	LQFP - VF	CDCLVP111MVFREP	LVP111MEP	V62/12624-01XE

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

DEVICE INFORMATION



PIN FUNCTIONS⁽¹⁾

PIN		DESCRIPTION
NAME	NO.	
CLK_SEL	2	Clock select. Used to select between CLK0 and CLK1 input pairs. LVTTTL/LVCMOS functionality compatible.
CLK0, $\overline{\text{CLK0}}$	3, 4	Differential LVECL/LVPECL input pair
CLK1, $\overline{\text{CLK1}}$	6, 7	
Q [9:0]	11, 13, 15, 18, 20, 22, 24, 27, 29, 31	LVECL/LVPECL clock outputs, these outputs provide low-skew copies of CLKn.
$\overline{\text{Q}}$ [9:0]	10, 12, 14, 17, 19, 21, 23, 26, 28, 30	LVECL/LVPECL complementary clock outputs, these outputs provide copies of $\overline{\text{CLKn}}$.
V _{BB}	5	Reference voltage output for single-ended input operation
V _{CC}	1, 9, 16, 25, 32	Supply voltage
V _{EE}	8	Device ground or negative supply voltage in ECL mode

(1) CLKn, CLK_SEL pull down resistor = 75 kΩ; $\overline{\text{CLKn}}$ pull up resistor = 37.5 kΩ; $\overline{\text{CLKn}}$ pull down resistor = 50 kΩ.

CDCLVP111-EP

SCAS933 – DECEMBER 2012

www.ti.com

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

		VALUE	UNIT
V_{CC}	Supply voltage (Relative to V_{EE})	-0.3 to 4.6	V
V_I	Input voltage	-0.3 to $V_{CC} + 0.5$	V
V_O	Output voltage	-0.3 to $V_{CC} + 0.5$	V
I_{IN}	Input current	±20	mA
V_{EE}	Negative supply voltage (Relative to V_{CC})	-4.6 to 0.3	V
I_{BB}	Sink/source current	-1 to 1	mA
I_O	DC output current	-50	mA
T_{stg}	Storage temperature range	-65 to 150	°C
T_J	Maximum operating junction temperature	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

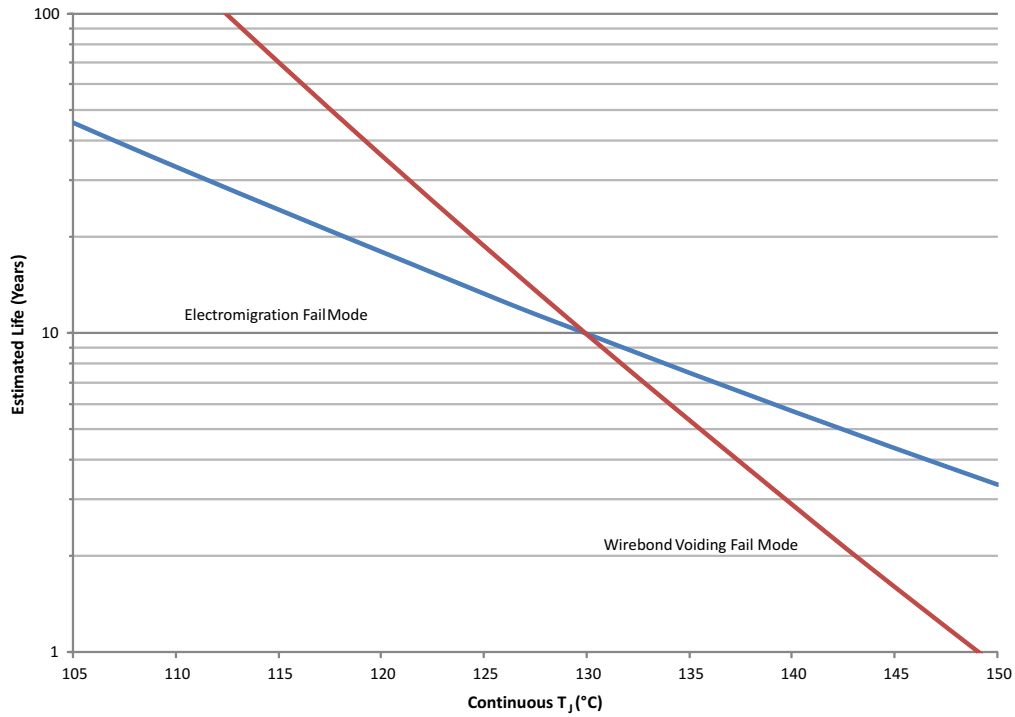
RECOMMENDED OPERATING CONDITIONS

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage (relative to V_{EE})	2.375	2.5/3.3	3.8	V
T_J	Operating junction temperature	-55		125	°C

PACKAGE THERMAL IMPEDANCE, VF (LQFP)

		TEST CONDITION	VALUE	UNIT
θ_{JA}	Thermal resistance junction to ambient ⁽¹⁾	0 LFM	74	°C/W
		150 LFM	66	°C/W
		250 LFM	64	°C/W
		500 LFM	61	°C/W
θ_{JC}	Thermal resistance junction to case		39	°C/W

(1) According to JESD 51-7 standard.



- (1) See data sheet for absolute maximum and minimum recommended operating conditions.
- (2) Silicon operating life design goal is 10 years at 105°C junction temperature (does not include package interconnect life).

Figure 1. CDCLVP111 in 32/VF Package Operating Life Derating Chart

LVECL DC ELECTRICAL CHARACTERISTICS

 Vsupply: $V_{CC} = 0\text{ V}$, $V_{EE} = -2.375\text{ V}$ to -3.8 V over operating temperature range $T_J = -55^\circ\text{C}$ to 125°C (unless otherwise noted)

PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	UNIT
I_{EE} Supply internal current	Absolute value of current	$-55^\circ\text{C}, 25^\circ\text{C}, 125^\circ\text{C}$	35		85	mA
I_{CC} Output and internal supply current	All outputs terminated $50\ \Omega$ to $V_{CC} - 2\text{ V}$	$-55^\circ\text{C}, 25^\circ\text{C}$			385	mA
		125°C			405	
I_{IN} Input current	Includes pullup/pulldown resistors, $V_{IH} = V_{CC}$, $V_{IL} = V_{CC} - 2\text{ V}$	$-55^\circ\text{C}, 25^\circ\text{C}, 125^\circ\text{C}$	-150		150	μA
V_{BB} Internally generated bias voltage	For $V_{EE} = -3$ to -3.8 V , $I_{BB} = -0.2\text{ mA}$	$-55^\circ\text{C}, 25^\circ\text{C}, 125^\circ\text{C}$	-1.45	-1.3	-1.125	V
	$V_{EE} = -2.375$ to -2.75 V , $I_{BB} = -0.2\text{ mA}$	$-55^\circ\text{C}, 25^\circ\text{C}, 125^\circ\text{C}$	-1.4	-1.25	-1.1	
V_{IH} High-level input voltage (CLK_SEL)		$-55^\circ\text{C}, 25^\circ\text{C}, 125^\circ\text{C}$	-1.165		-0.88	V
V_{IL} Low-level input voltage (CLK_SEL)		$-55^\circ\text{C}, 25^\circ\text{C}, 125^\circ\text{C}$	-1.81		-1.475	V
V_{ID} Input amplitude (CLKn, $\overline{\text{CLKn}}$)	Difference of input, See ⁽¹⁾ $ V_{IH} - V_{IL} $	$-55^\circ\text{C}, 25^\circ\text{C}, 125^\circ\text{C}$	0.5		1.3	V
V_{CM} Common-mode voltage (CLKn, $\overline{\text{CLKn}}$)	DC offset relative to V_{EE}	$-55^\circ\text{C}, 25^\circ\text{C}, 125^\circ\text{C}$	$V_{EE} + 1$		-0.3	V
V_{OH} High-level output voltage	$I_{OH} = -21\text{ mA}$	-55°C	-1.26		-0.85	V
		25°C	-1.2		-0.85	
		125°C	-1.15		-0.8	
V_{OL} Low-level output voltage	$I_{OL} = -5\text{ mA}$	25°C	-1.85		-1.425	V
		$-55^\circ\text{C}, 125^\circ\text{C}$	-1.85		-1.25	
V_{OD} Differential output voltage swing	Terminated with $50\ \Omega$ to $V_{CC} - 2\text{ V}$, See Figure 4	$-55^\circ\text{C}, 25^\circ\text{C}, 125^\circ\text{C}$	400			mV

 (1) V_{ID} minimum and maximum is required to maintain ac specifications, actual device function tolerates a minimum V_{ID} of 100 mV.

LVPECL DC ELECTRICAL CHARACTERISTICS

Vsupply: $V_{CC} = 2.375\text{ V to }3.8\text{ V}$, $V_{EE} = 0\text{ V}$ over operating temperature range $T_J = -55^\circ\text{C to }125^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT			
I_{EE}	Supply internal current	Absolute value of current		-55°C, 25°C, 125°C	35	85	mA	
I_{CC}	Output and internal supply current	All outputs terminated 50 Ω to $V_{CC} - 2\text{ V}$		-55°C, 25°C		385	mA	
				125°C		405		
I_{IN}	Input current	Includes pullup/pulldown resistors $V_{IH} = V_{CC}$, $V_{IL} = V_{CC} - 2\text{ V}$		-55°C, 25°C, 125°C	-150	150	μA	
V_{BB}	Internally generated bias voltage	$V_{CC} = 3\text{ to }3.8\text{ V}$, $I_{BB} = -0.2\text{ mA}$		-55°C, 25°C, 125°C	$V_{CC} - 1.45$	$V_{CC} - 1.3$	$V_{CC} - 1.125$	V
		$V_{CC} = 2.375\text{ to }2.75\text{ V}$, $I_{BB} = -0.2\text{ mA}$		-55°C, 25°C, 125°C	$V_{CC} - 1.4$	$V_{CC} - 1.25$	$V_{CC} - 1.1$	
V_{IH}	High-level input voltage (CLK_SEL)			-55°C, 25°C, 125°C	$V_{CC} - 1.165$	$V_{CC} - 0.88$	V	
V_{IL}	Low-level input voltage (CLK_SEL)			-55°C, 25°C, 125°C	$V_{CC} - 1.81$	$V_{CC} - 1.475$	V	
V_{ID}	Input amplitude (CLKn, $\overline{\text{CLKn}}$)	Difference of input, see ⁽¹⁾ , $ V_{IH} - V_{IL} $		-55°C, 25°C, 125°C	0.5	1.3	V	
V_{CM}	Common-mode voltage (CLKn, $\overline{\text{CLKn}}$)	DC offset relative to V_{EE}		-55°C, 25°C, 125°C	1	$V_{CC} - 0.3$	V	
V_{OH}	High-level output voltage	$I_{OH} = -21\text{ mA}$		-55°C	$V_{CC} - 1.26$	$V_{CC} - 0.85$	V	
				25°C	$V_{CC} - 1.2$	$V_{CC} - 0.85$		
				125°C	$V_{CC} - 1.15$	$V_{CC} - 0.8$		
V_{OL}	Low-level output voltage	$I_{OL} = -5\text{ mA}$		25°C	$V_{CC} - 1.85$	$V_{CC} - 1.425$	V	
				-55°C, 125°C	$V_{CC} - 1.85$	$V_{CC} - 1.25$		
V_{OD}	Differential output voltage swing	Terminated with 50 Ω to $V_{CC} - 2\text{ V}$, See Figure 4		-55°C, 25°C, 125°C	400		mV	

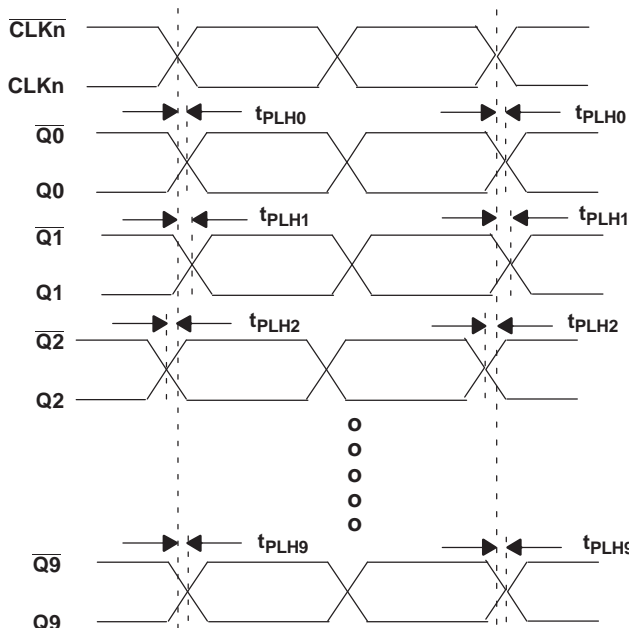
(1) V_{ID} minimum and maximum is required to maintain ac specifications, actual device function tolerates a minimum V_{ID} of 100 mV.

AC ELECTRICAL CHARACTERISTICS

Vsupply: $V_{CC} = 2.375\text{ V to }3.8\text{ V}$, $V_{EE} = 0\text{ V}$ or LVECL/LVPECL input $V_{CC} = 0\text{ V}$, $V_{EE} = -2.375\text{ V to }-3.8\text{ V}$ over operating temperature range $T_J = -55^\circ\text{C to }125^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
t_{pd}	Differential propagation delay CLKn, CLKn to all Q0, Q0... Q9, Q9	See Note D in Figure 2		200	355	ps
$t_{sk(o)}$	Output-to-output skew	See Notes A and D in Figure 2		15	50	ps
$t_{sk(pp)}$	Part-to-part skew	See Notes B and D in Figure 2		70		ps
t_{aj}	Additive phase jitter ⁽¹⁾	Integration bandwidth of 20 kHz to 20 MHz, fout = 200 MHz at 25°C		0.125	0.8	ps
$f_{(max)}$	Maximum frequency ⁽¹⁾	Functional up to 3.5 GHz, see Figure 4			3500	MHz
t_r/t_f	Output rise and fall time (20%, 80%)	See Note D in Figure 2			240	ps

(1) Specification is guaranteed by bench characterization and is not tested in production.



- A. Output skew is calculated as the greater of: The difference between the fastest and the slowest t_{PLHn} ($n = 0, 1, \dots, 9$) or the difference between the fastest and the slowest t_{pHLn} ($n = 0, 1, \dots, 9$).
- B. Part-to-part skew, is calculated as the greater of: The difference between the fastest and the slowest t_{PLHn} ($n = 0, 1, \dots, 9$) across multiple devices or the difference between the fastest and the slowest t_{pHLn} ($n = 0, 1, \dots, 9$) across multiple devices.
- C. Typical value measured at ambient when clock input is 155.52 MHz for an integration bandwidth of 20 kHz to 5 MHz.
- D. Input conditions: $V_{CM} = 1\text{ V}$, $V_{ID} = 0.5\text{ V}$ and $F_{IN} = 1\text{ GHz}$.

Figure 2. Waveform for Calculating Both Output and Part-to-Part Skew

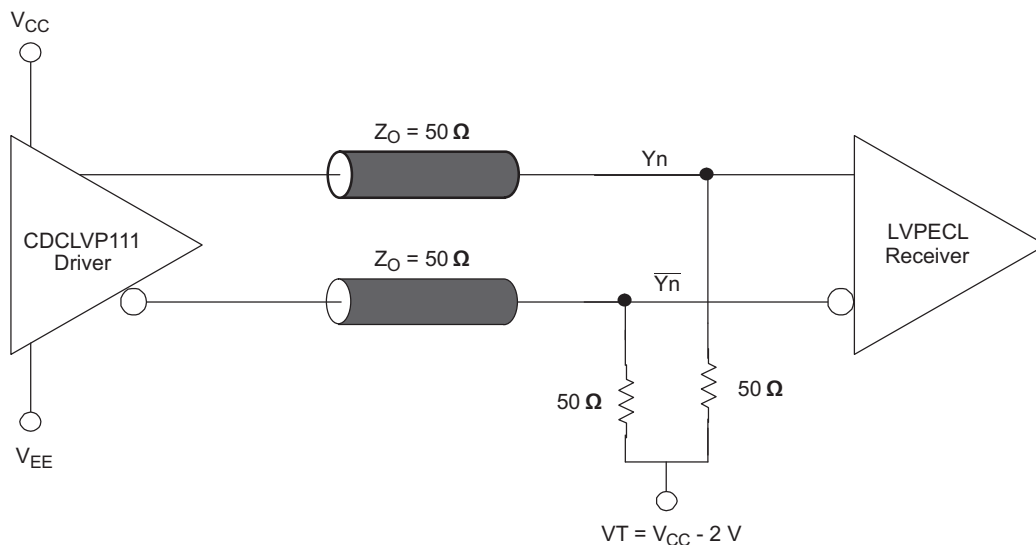


Figure 3. Typical Termination for Output Driver (See the Interfacing Between LVPECL, LVDS, and CML Application Note, Literature Number [SCAA056](#))

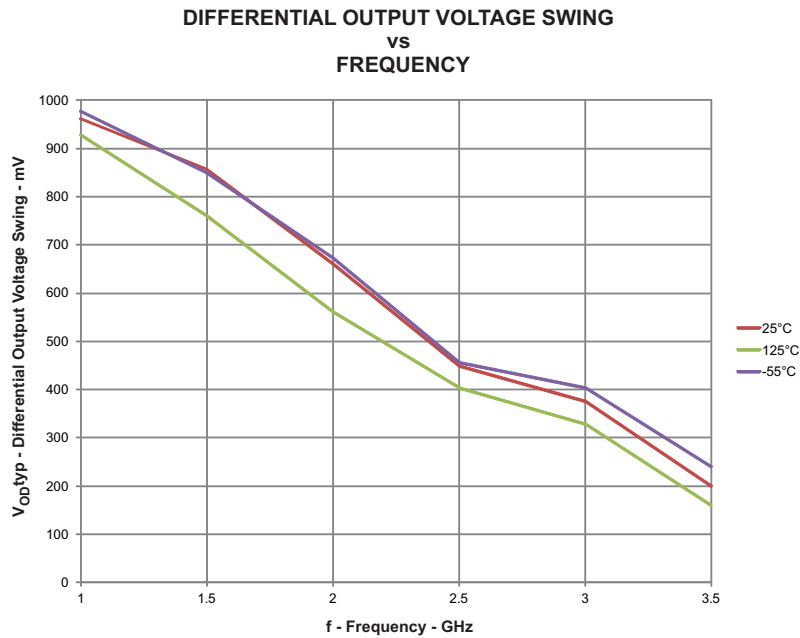


Figure 4. LVPECL Input Using CLK0 Pair, $V_{CC} = 2.375\text{ V}$, $V_{CM} = 1\text{ V}$, $V_{ID} = 0.5\text{ V}$

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CDCLVP111MVFREP	Active	Production	LQFP (VF) 32	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-55 to 125	LVP111MEP
V62/12624-01XE	Active	Production	LQFP (VF) 32	1000 LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-55 to 125	LVP111MEP

(1) **Status:** For more details on status, see our [product life cycle](#).

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF CDCLVP111-EP :

- Catalog : [CDCLVP111](#)

- Space : [CDCLVP111-SP](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

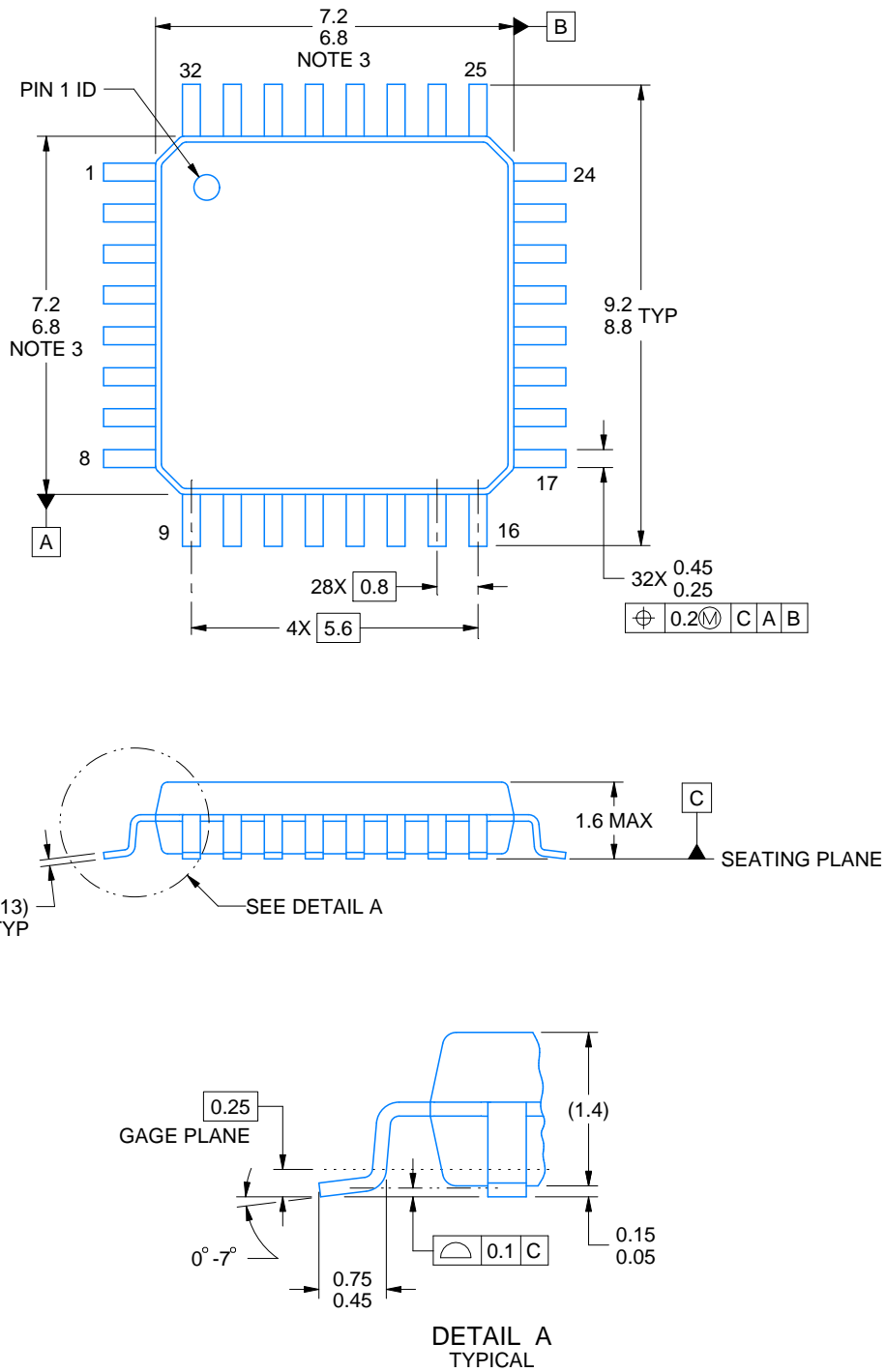
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CDCLVP111MVFREP	LQFP	VF	32	1000	330.0	16.4	9.6	9.6	1.9	12.0	16.0	Q2

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDCLVP111MVFREP	LQFP	VF	32	1000	367.0	367.0	38.0



4219769/A 04/2019

NOTES:

PowerPAD is a trademark of Texas Instruments.

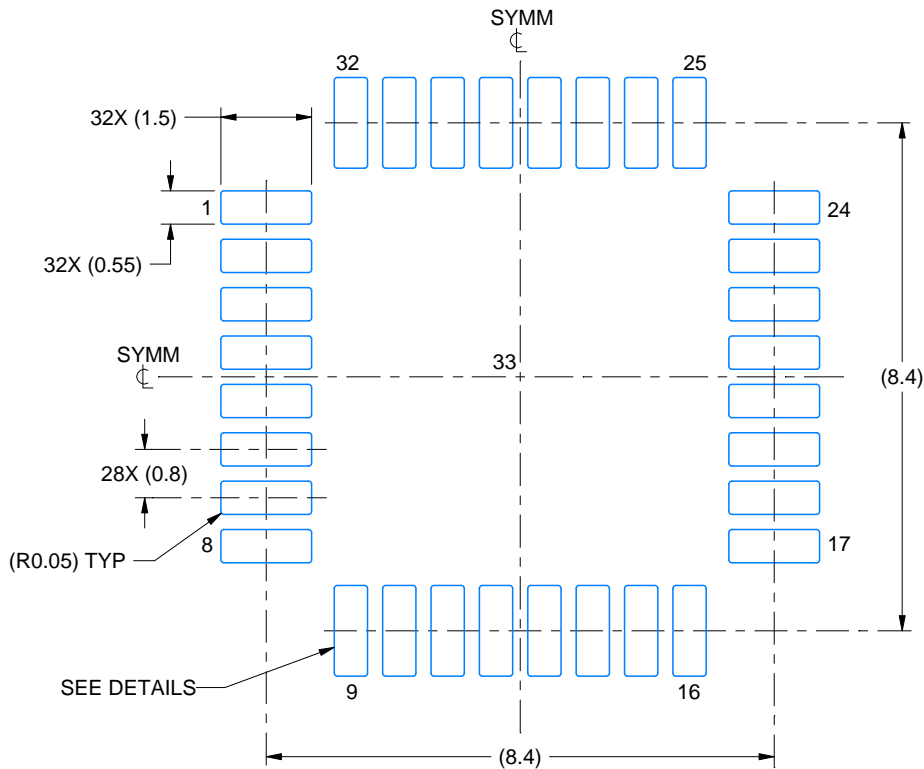
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs.
4. Reference JEDEC registration MS-026.

EXAMPLE BOARD LAYOUT

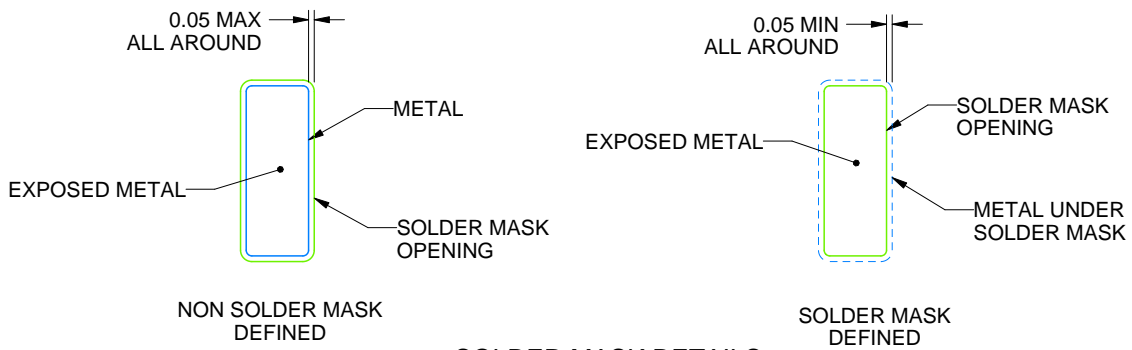
VF0032A

LQFP - 1.6 mm max height

PLASTIC QUAD FLATPACK



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4219769/A 04/2019

NOTES: (continued)

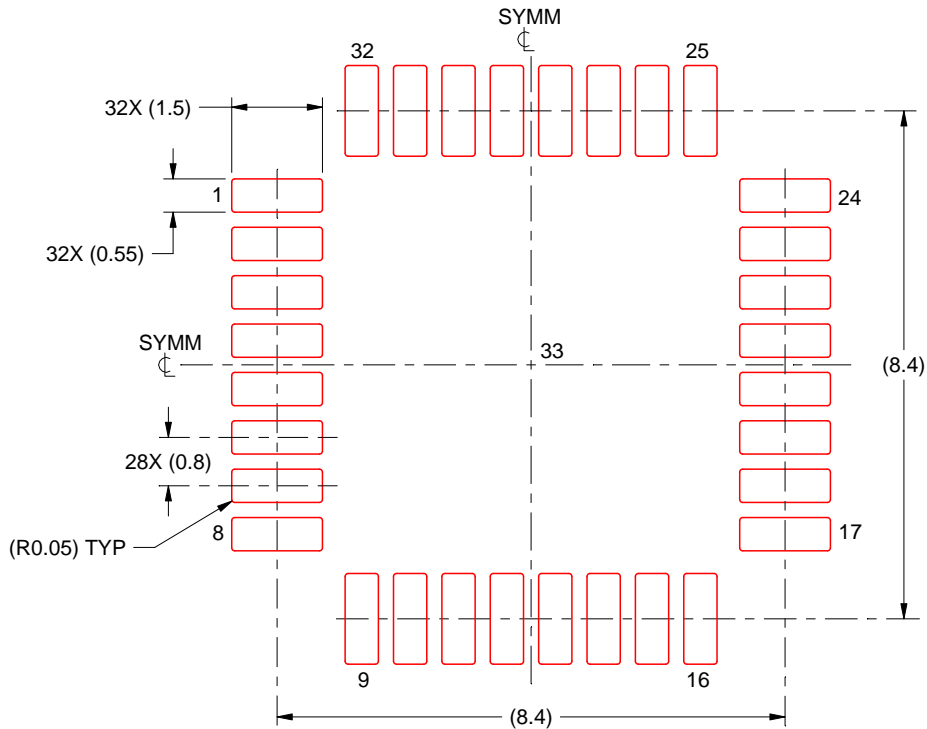
- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

VF0032A

LQFP - 1.6 mm max height

PLASTIC QUAD FLATPACK



SOLDER PASTE EXAMPLE
SCALE:8X

4219769/A 04/2019

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#), [TI's General Quality Guidelines](#), or other applicable terms available either on [ti.com](#) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025